

HAMELIN ET AL. - 10/705,200
Client/Matter: 071469-0306773

IN THE SPECIFICATION:

On page 1, paragraph [0002] is amended as follows:

[0002] This application is related to co-pending United States patent application serial no. 10/705,201, entitled "Processing System and Method for Treating a Substrate", filed on November 12, 2003; co-pending United States patent application serial no. 10/704,969, entitled "Processing System and Method for Thermally Treating a Substrate", filed on November 12, 2003; and co-pending United States patent application serial no. 10/705,397, entitled "Method and Apparatus for Thermally Insulating Adjacent Temperature Controlled Chambers", filed on November 12, 2003. The entire contents of all of those applications are herein incorporated by reference in their entirety.

On page 20, paragraph [0067] is amended as follows:

[0067] FIGs. 12, 13, and 14 depict a side view, a top view, and a side cross-sectional view, respectively, of thermal insulation assembly 230. A similar assembly can also be used as thermal insulation assembly 50, 150 or 650. The thermal insulation assembly 230 can comprise an interface plate 231 coupled to, for example, the chemical treatment chamber 211, as shown in FIG. 12, and configured to form a structural contact between the thermal treatment chamber 221 (see FIG. 14) and the chemical treatment chamber 211, and an insulator plate 232 coupled to the interface plate 231 and configured to reduce the thermal contact between the thermal treatment chamber 221 and the chemical treatment chamber 211. Furthermore, in FIG. 12, the interface plate 231 comprises one or more structural contact members 233 having a mating surface 234 configured to couple with a mating surface on the thermal treatment chamber 221. The interface plate 231 can be fabricated from a metal, such as aluminum, stainless steel, etc., in order to form a rigid contact between the two chambers 211, 221. The insulator plate 232 can be fabricated from a material having a low thermal conductivity such as Teflon, alumina, quartz, etc. A thermal insulation assembly is described in greater detail in pending U.S. Application No. 10/705,397, filed on even date herewith and entitled, "Method and apparatus for thermally insulating adjacent temperature controlled chambers", and it is incorporated by reference in its entirety.